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Commissioner for Patents
P.O. Box 1450
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Sir:

The patent application of

Inventor(s): Rikiya KATOH et al

For: LEAD-FREE SOLDER BALL

is attached for filing.

[X] This application is being filed without a declaration or fee.

[X] This application claims the priority of Japanese Patent Application No. 2002-303197 filed on October 17, 2002.

Respectfully submitted,

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